

CLAIMS

1. A method for gluing a circuit component (17) to a circuit board (1), wherein in a contact area (2) between the circuit component (17) and the circuit board (1), adhesive dots (4) are placed in a regular pattern and are brought to merge by pressing the circuit component (17) and the circuit board (1) against each other, characterized in that before placing the dots (4) of the regular pattern, at least one fore-running adhesive dot (14) is placed inside the contact area (2).
2. The method of claim 1, characterized in that several fore-running adhesive dots (14) are placed along a line (21).
3. The method of one of the preceding claims, characterized in that the amount of adhesive contained in the fore-running adhesive dots (14) is less than a tenth of the amount of adhesive contained in the adhesive dots (4) of the regular pattern.
4. A method for gluing a circuit component (17) to a circuit board (1), wherein in a contact area (2) between the circuit component (17) and the circuit board (1), adhesive dots (13) are placed in a regular pattern and are brought to merge by pressing the circuit component (17) and the circuit board (1) against each other, in particular according to one of the preceding claims, characterized in that an additional adhesive dot (15) is placed adjacent to a corner of the regular pattern.
5. The method of claim 4, characterized in that the corner of regular pattern corresponds to a corner of the circuit component (17), and that the additional

adhesive dot (15) is placed on a bisectrix of the corner of the circuit component (17).

6. The method of claim 4 or 5, characterized in that the distance of the additional adhesive dot (15) from an adjacent edge of the circuit component (17) is made smaller than the distance of the dots (4) of the regular pattern from that edge.
7. The method of one of the preceding claims, characterized in that the amount of adhesive contained in the adhesive dots (4) of the regular pattern is set for a thickness of the adhesive layer (22) between the circuit board (1) and the circuit component (17) of approx. 2 to 10 μm , preferably approx. 5 μm .
8. The method of one of the preceding claims, characterized in that an epoxy resin loaded with metal particles is used as the adhesive.
9. The method of one of the preceding claims, characterized in that the adhesive dots (4) are placed using a nozzle (11) through which the adhesive flows.